IRP1608N06-B50

SMD Type 940nm Infrared Emitter

Features

- Small double-end package
- Viewing Angle = $\pm 75^0$
- High reliability
- Good spectral matching to Si photo detector
- RoHS compliance

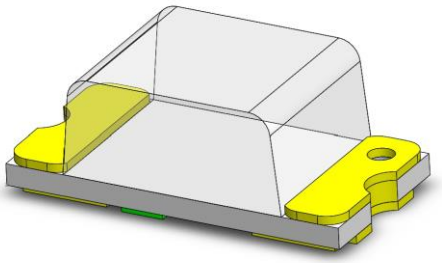
Description

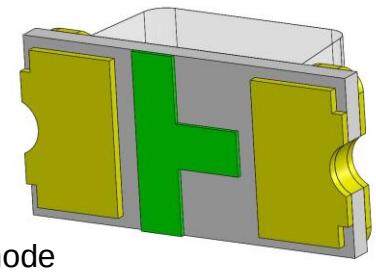
The IRP1608N06-B50 is a GaAlAs infrared LED housed in a miniature SMD package. The device has a peak wavelength of 940nm LED spectrally matched with phototransistor or photodiode.

Applications

- Infrared sensor

Package Outline

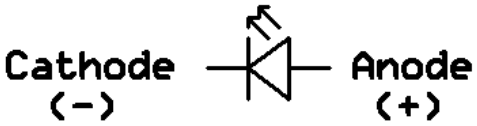




Anode

Cathode

Schematic



Absolute Maximum Rating at 25^{0}C

Symbol	*Parameters*	*Ratings*	*Units*	*Notes*
I_F	Continuous Forward Current	70	mA	
I_{FP}	Peak Forward Current	0.7	A	1
V_R	Reverse Voltage	5	V	
T_{opr}	Operating Temperature	-40 ~ +85	^{0}C	
T_{stg}	Storage Temperature	-40 ~ +100	^{0}C	
T_{sol}	Soldering Temperature	260	^{0}C	2
P_D	Power Dissipation at(or below) 25℃Free Air Temperature	119	mW	

Electro-Optical Characteristics *TA = 25°C (unless otherwise specified)*

Optical Characteristics

Symbol	*Parameters*	*Test Conditions*	*Min*	*Typ*	*Max*	*Units*	*Notes*
Ie	Radiant Intensity	I_F=20mA	0.4	0.8	1.3	mW/sr	3
		I_F =70mA	-	2.5	-		
λp	Peak Wavelength	I_F=20mA	-	940	-	nm	
Δλ	Spectral Bandwidth	I_F=20mA	-	50	-	nm	
θ1/2	Angle of Half Intensity	I_F=20mA	-	±75	-	deg	

Electrical Characteristics

Symbol	*Parameters*	*Test Conditions*	*Min*	*Typ*	*Max*	*Units*	*Notes*
V_F	Forward Voltage	I_F=20mA	1.0	1.2	1.5	V	
		I_F=70mA	1.1	1.34	1.7		
I_R	Reverse Current	V_R=5V	-	-	10	μA	

Notes:

1. I_{FP} Conditions--Pulse Width≦ 100μs and Duty≦ 1%.
2. Soldering time≦ 5 seconds.
3. Ie Bin Rank :

Bin Code	B	C
Min	0.4	0.65
Max	0.8	1.3

Typical Characteristic Curves

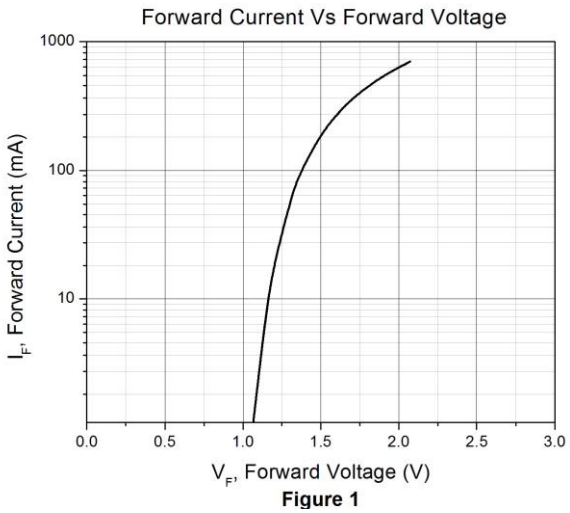


Figure 1

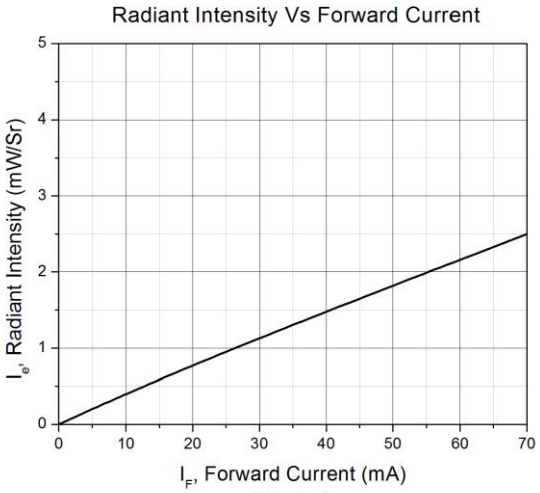


Figure 2

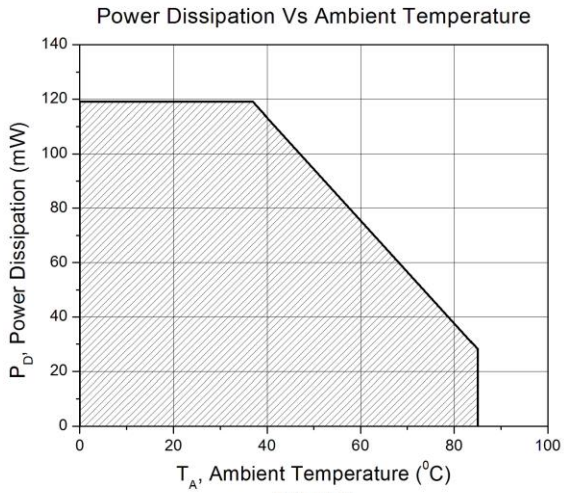


Figure 3

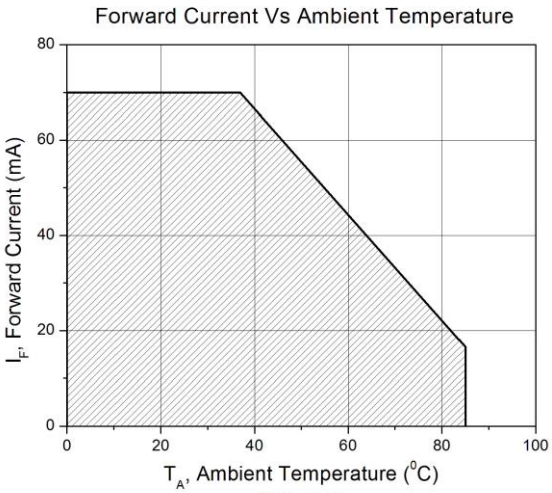


Figure 4

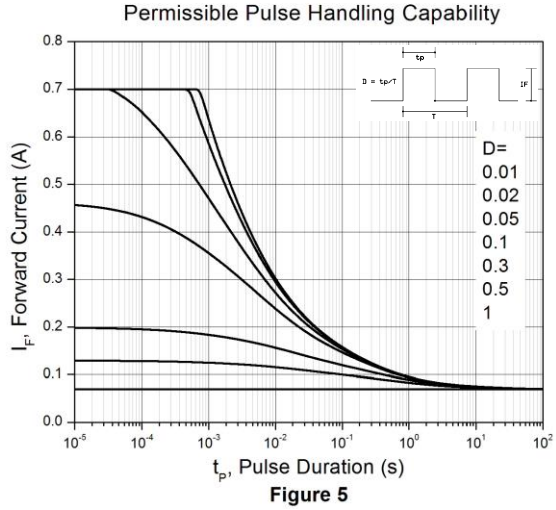


Figure 5

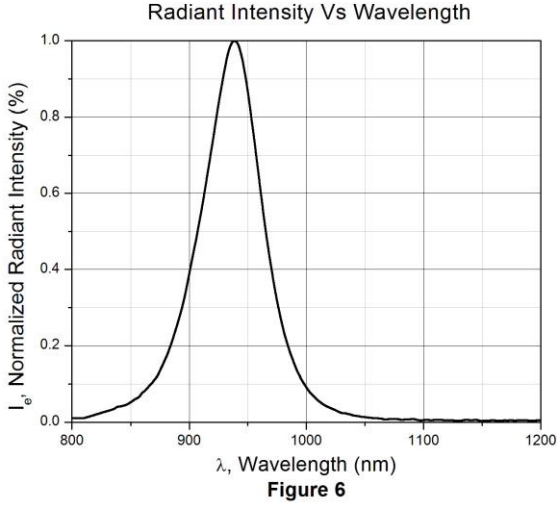


Figure 6

Typical Characteristic Curves

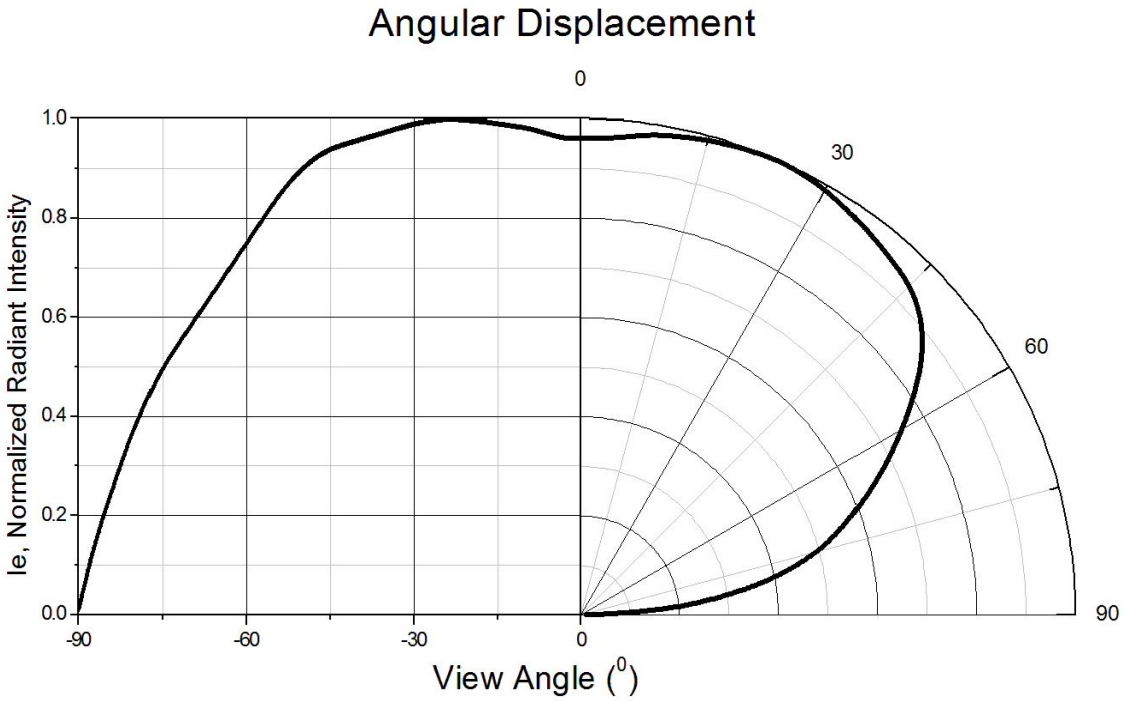
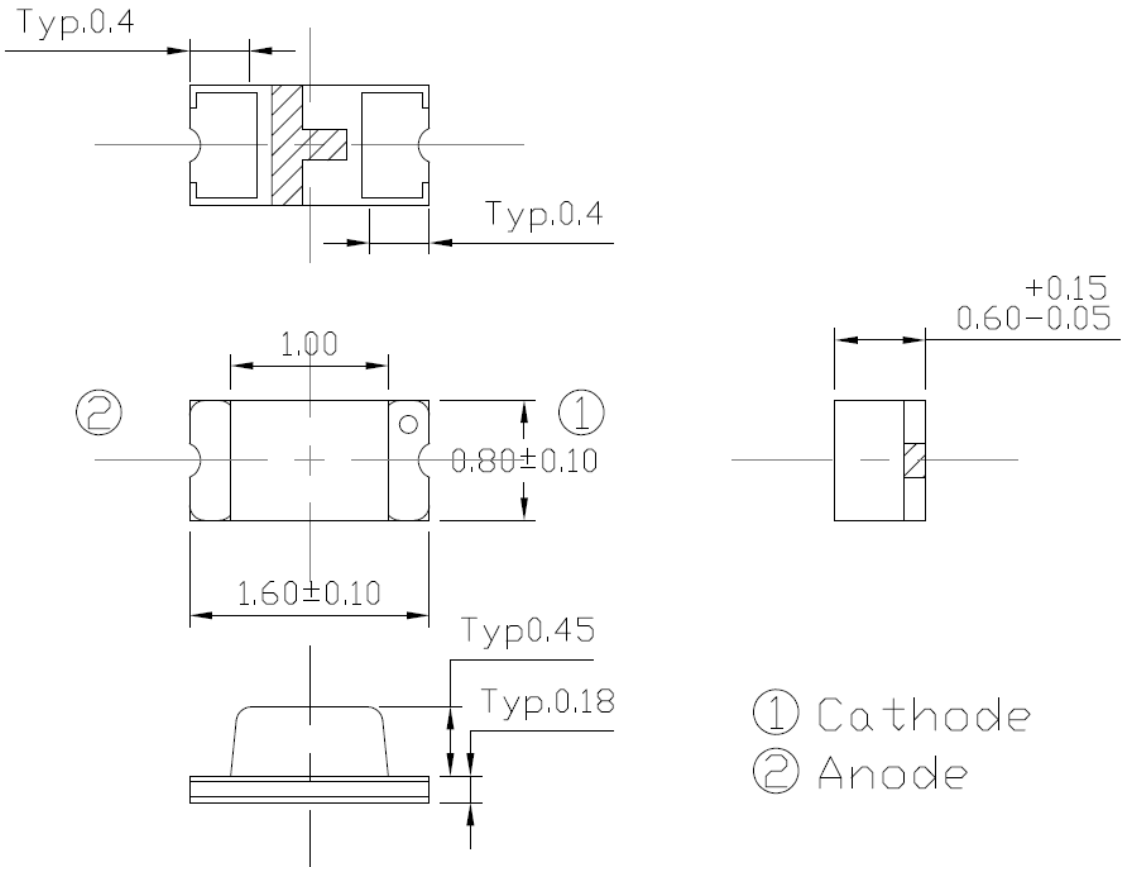
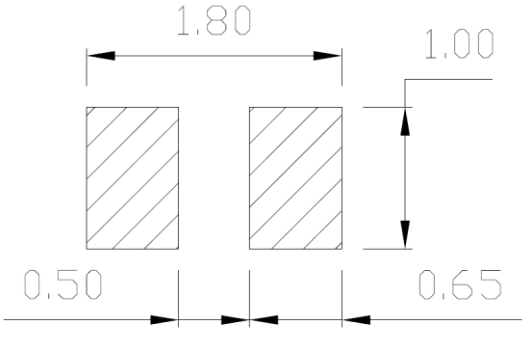


Figure 7

Package Dimension *All dimensions are in mm, unless otherwise stated*



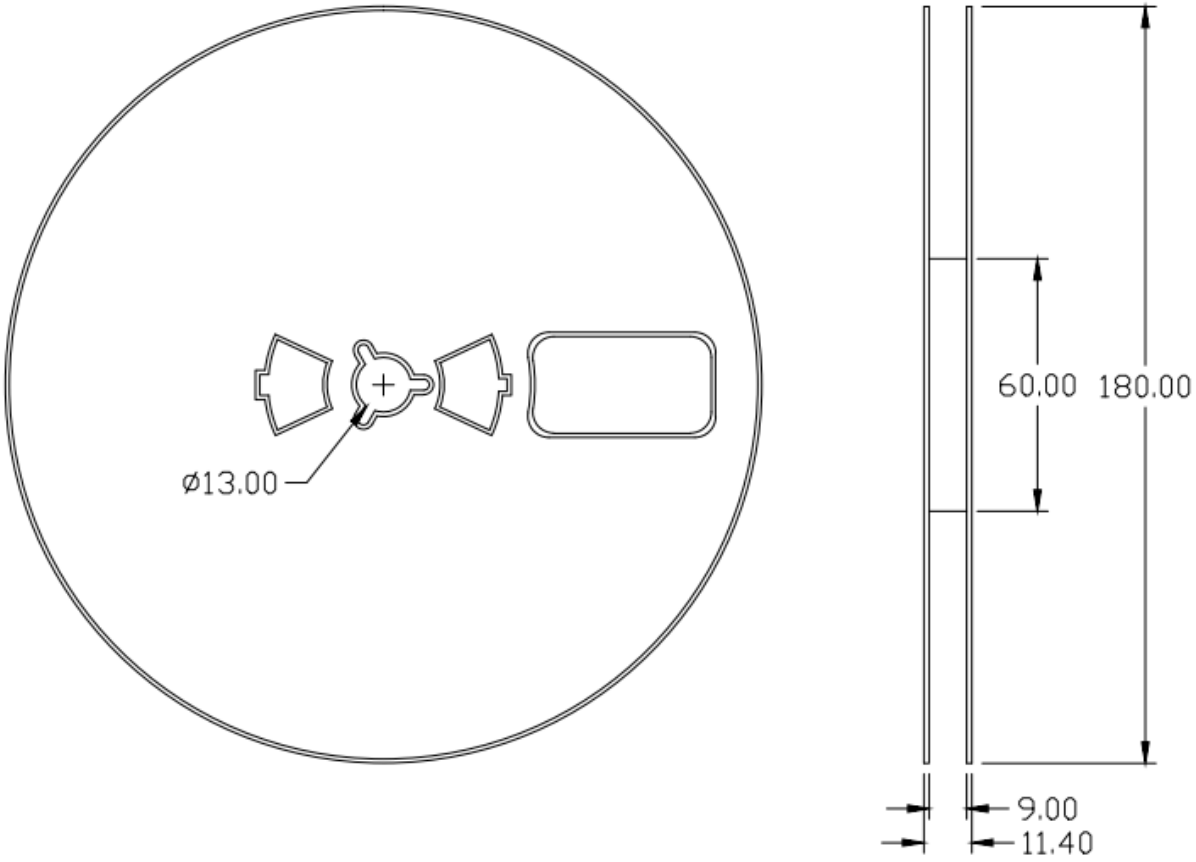
Recommended Soldering Mask *All dimensions are in mm, unless otherwise stated*



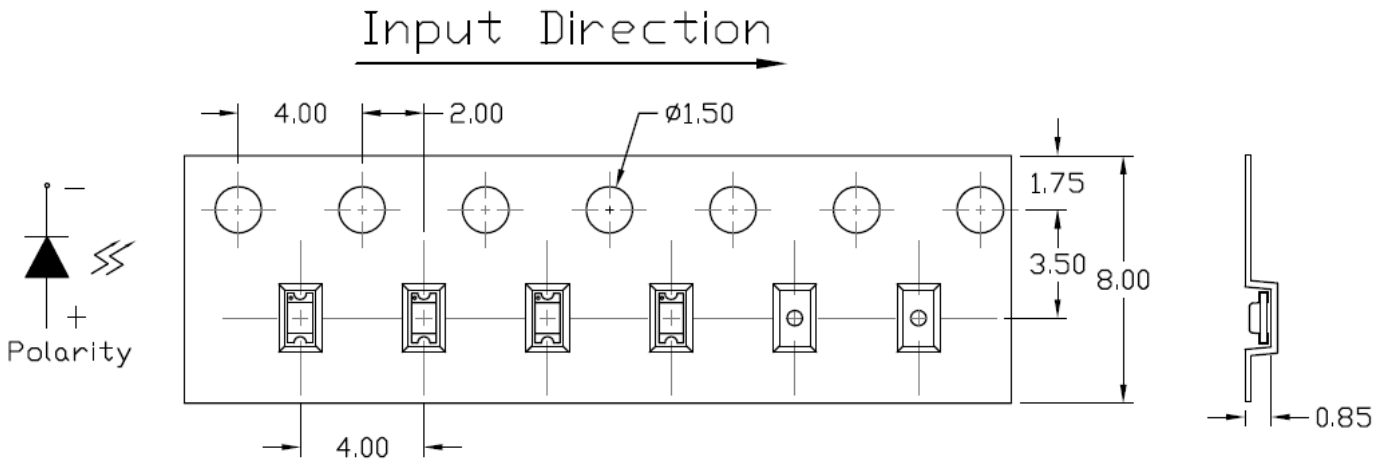
Ordering Information

Part Number	*Description*	*Quantity*
IRP1608N06-B50	Tape & Reel	4000 pcs

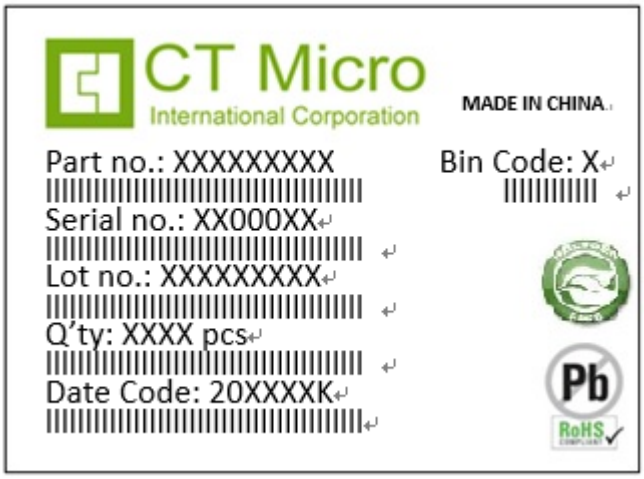
Reel Dimension *All dimensions are in mm, unless otherwise stated*



Tape Dimension *All dimensions are in mm, unless otherwise stated*



Label Form Specification



Part no: CTM Production Number

Serial no: Production Number

Lot no: Lot number

Q'ty: Packing Quantity

Date Code: Manufacture Date

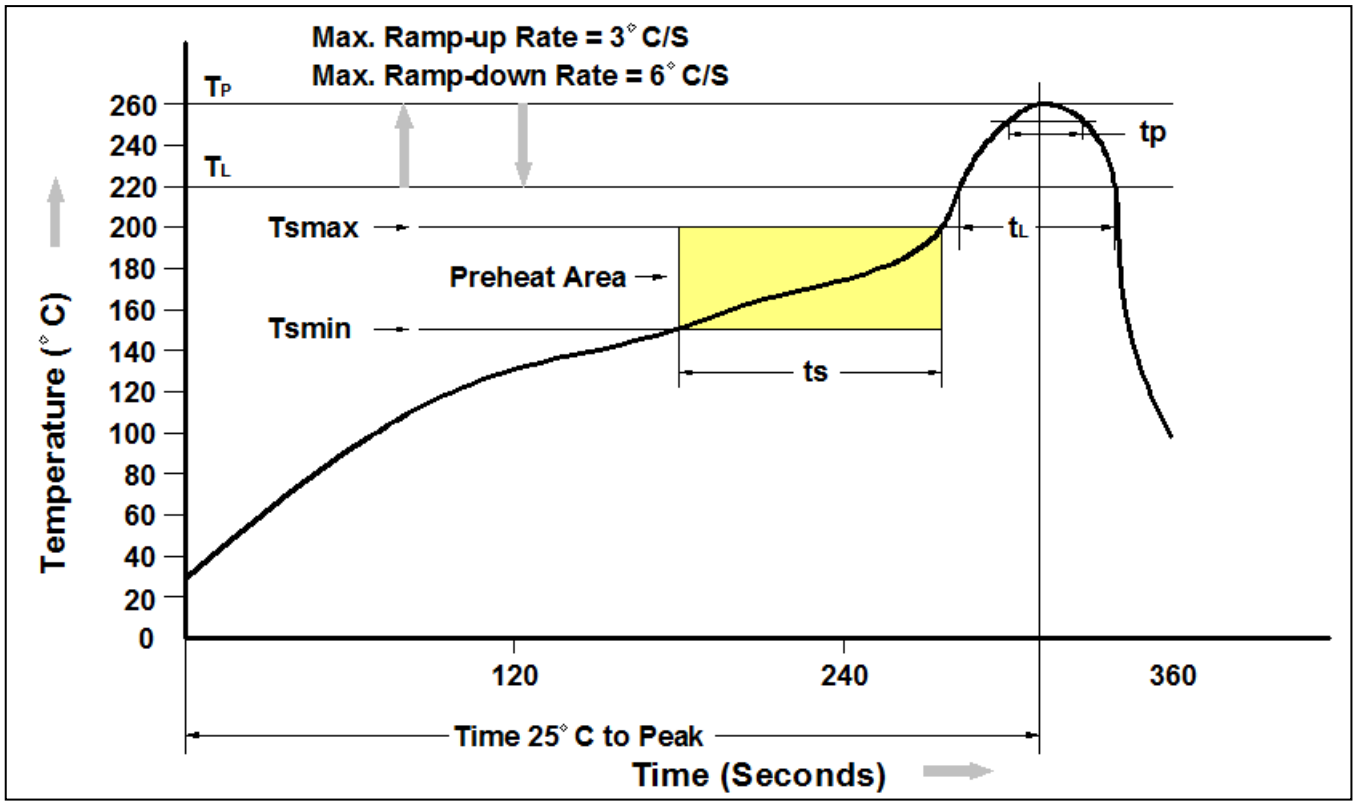
Bin Code: Ie Ranks

MADE IN CHINA: Production Place

Storage Condition

1. Do not open moisture proof bag before the products are ready to use.
2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening. Shelf life of non-opened bag is 12 months after the bag sealing date.
3. After opening the moisture barrier bag floor life is 168h at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.

Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t_L to t_P)	3°C/second max.
Liquidous Temperature (T_L)	217°C
Time (t_L) Maintained Above (T_L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t_P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

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